



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SO-8					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	1560	780 000	200 °C + N2	0	0.00
HAST	5270	668 600	130 °C, 85 % RH	0	0.00
Power Cycle	3854	57 798 192	DELTA T _J = 100 °C	0	0.00
Pressure Pot	5556	715 008	121°, 15 PSIG	0	0.00
Solder DUNK	2421	7263	260 °C, 10 s	0	0.00
Solderability	765	6240	883 M2003	0	0.00
Temp. Cycle	5346	5 742 172	-55 °C to 150 °C	0	0.00